Functional Safety Information

TMUX6219-Q1
Functional Safety FIT Rate, FMD and Pin FMA

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Trademarks

1 Overview

This document contains information for TMUX6219-Q1 (DGK-8 package) to aid in a functional safety system design. Information provided are:

- Functional Safety Failure In Time (FIT) rates of the semiconductor component estimated by the application of industry reliability standards
- Component failure modes and their distribution (FMD) based on the primary function of the device
- Pin failure mode analysis (Pin FMA)

Figure 1-1 shows the device functional block diagram for reference.

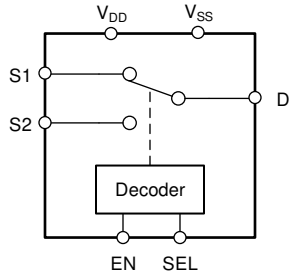

Figure 1-1. Functional Block Diagram

TMUX6219-Q1 was developed using a quality-managed development process, but was not developed in accordance with the IEC 61508 or ISO 26262 standards.

2 Functional Safety Failure In Time (FIT) Rates

This section provides Functional Safety Failure In Time (FIT) rates for TMUX6219-Q1 based on two different industry-wide used reliability standards:

- Table 2-1 provides FIT rates based on IEC TR 62380 / ISO 26262 part 11
- Table 2-2 provides FIT rates based on the Siemens Norm SN 29500-2

Table 2-1. Component Failure Rates per IEC TR 62380 / ISO 26262 Part 11

FIT IEC TR 62380 / ISO 26262	FIT (Failures Per 10^9 Hours)
Total Component FIT Rate	8
Die FIT Rate	4
Package FIT Rate	4

The failure rate and mission profile information in Table 2-1 comes from the Reliability data handbook IEC TR 62380 / ISO 26262 part 11:

- Mission Profile: Motor Control from Table 11
- Power dissipation: 100 mW
- Climate type: World-wide Table 8
- Package factor (lambda 3): Table 17b
- Substrate Material: FR4
- EOS FIT rate assumed: 0 FIT

Table 2-2. Component Failure Rates per Siemens Norm SN 29500-2

Table	Category	Reference FIT Rate	Reference Virtual T_J
5	BICMOS ASICs Analog and Mixed =<50 V supply	20 FIT	55°C

The Reference FIT Rate and Reference Virtual T_J (junction temperature) in Table 2-2 come from the Siemens Norm SN 29500-2 tables 1 through 5. Failure rates under operating conditions are calculated from the reference failure rate and virtual junction temperature using conversion information in SN 29500-2 section 4.

3 Failure Mode Distribution (FMD)

The failure mode distribution estimation for TMUX6219-Q1 in Table 3-1 comes from the combination of common failure modes listed in standards such as IEC 61508 and ISO 26262, the ratio of sub-circuit function size and complexity and from best engineering judgment.

The failure modes listed in this section reflect random failure events and do not include failures due to misuse or overstress.

Table 3-1. Die Failure Modes and Distribution

Die Failure Modes	Failure Mode Distribution (%)
MUX no output (HIZ)	20%
MUX channel stuck on	10%
MUX channel stuck off	10%
MUX functional out of specification voltage or timing	60%

The FMD in Table 3-1 excludes short circuit faults across the isolation barrier. Faults for short circuit across the isolation barrier can be excluded according to ISO 61800-5-2:2016 if the following requirements are fulfilled:

1. The signal isolation component is OVC III according to IEC 61800-5-1. If a SELV/PELV power supply is used, pollution degree 2/OVC II applies. All requirements of IEC 61800-5-1:2007, 4.3.6 apply.
2. Measures are taken to ensure that an internal failure of the signal isolation component cannot result in excessive temperature of its insulating material.

Creepage and clearance requirements should be applied according to the specific equipment isolation standards of an application. Care should be taken to maintain the creepage and clearance distance of a board design to ensure that the mounting pads of the isolator on the printed-circuit board do not reduce this distance.

4 Pin Failure Mode Analysis (Pin FMA)

This section provides a Failure Mode Analysis (FMA) for the pins of the TMUX6219-Q1. The failure modes covered in this document include the typical pin-by-pin failure scenarios:

- Pin short-circuited to Ground (see Table 4-2)
- Pin open-circuited (see Table 4-3)
- Pin short-circuited to an adjacent pin (see Table 4-4)
- Pin short-circuited to supply (see Table 4-5)

Table 4-2 through Table 4-5 also indicate how these pin conditions can affect the device as per the failure effects classification in Table 4-1.

Table 4-1. TI Classification of Failure Effects

Class	Failure Effects
A	Potential device damage that affects functionality
B	No device damage, but loss of functionality
C	No device damage, but performance degradation
D	No device damage, no impact to functionality or performance

Figure 4-1 shows the TMUX6219-Q1 pin diagram. For a detailed description of the device pins please refer to the *Pin Configuration and Functions* section in the TMUX6219-Q1 data sheet.

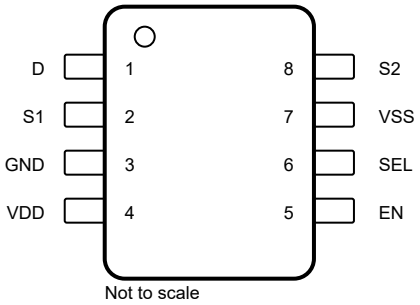

Figure 4-1. Pin Diagram

Table 4-2. Pin FMA for Device Pins Short-Circuited to Ground

Pin Name	Pin No.	Description of Potential Failure Effect(s)	Failure Effect Class
D	1	Corruption of the signal passed onto the S pins. If there is no limiting resistor in the switch path, then device damage is possible.	A
S1	2	Corruption of the signal passed onto the D pin. If there is no limiting resistor in the switch path, then device damage is possible.	A
GND	3	There is no effect; this is normal operation.	D
VDD	4	Device is unpowered and not functional.	B
EN	5	Enable is stuck low. Can no longer turn off the device.	B
IN	6	Address is stuck low. Cannot control switch states.	B
VSS	7	There is no effect; this is normal operation, if the switch path signal voltages are positive. Possible damage to the device if the switch path signal voltages are negative. Observe that the absolute maximum ratings for all pins of the device are met, otherwise device damage may be plausible.	A
S2	8	Corruption of the signal passed onto the D pin. If there is no limiting resistor in the switch path, then device damage is possible.	A

Table 4-3. Pin FMA for Device Pins Open-Circuited

Pin Name	Pin No.	Description of Potential Failure Effect(s)	Failure Effect Class
D	1	Corruption of the signal passed onto the S pins.	B
S1	2	Corruption of the signal passed onto the D pin.	B
GND	3	Device is unpowered and not functional.	B
VDD	4	Device is unpowered and not functional.	B
EN	5	Loss of control of the EN pin. Cannot turn off the device.	B
IN	6	Loss of control of the address pin. Cannot control the switch.	B
VSS	7	Device is unpowered and not functional.	B
S2	8	Corruption of the signal passed onto the D pin.	B

Table 4-4. Pin FMA for Device Pins Short-Circuited to Adjacent Pin

Pin Name	Pin No.	Shorted to	Description of Potential Failure Effect(s)	Failure Effect Class
D	1	S1	Possible corruption of the signal passed onto the SX and D pin.	B
S1	2	GND	Corruption of the signal passed onto the D pin. If there is no limiting resistor in the switch path, then device damage is possible.	A
GND	3	VDD	Device is unpowered and not functional. Observe that the absolute maximum ratings for all pins of the device are met, otherwise device damage may be plausible.	A
VDD	4	EN	Not considered. This is a corner pin.	D
EN	5	IN	Loss of control of the switch state.	B

Table 4-4. Pin FMA for Device Pins Short-Circuited to Adjacent Pin (continued)

Pin Name	Pin No.	Shorted to	Description of Potential Failure Effect(s)	Failure Effect Class
IN	6	VSS	Possible damage to device if the signal voltage is negative. Observe that the absolute maximum ratings for all pins of the device are met, otherwise device damage may be plausible.	A
VSS	7	S2	Corruption of the signal passed onto the D pin. If there is no limiting resistor in the switch path, then device damage is possible.	A
S2	8	D	Not considered. This is a corner pin.	D

Table 4-5. Pin FMA for Device Pins Short-Circuited to VDD

Pin Name	Pin No.	Description of Potential Failure Effect(s)	Failure Effect Class
D	1	Corruption of the signal passed onto the S pins. If there is no limiting resistor in the switch path, then device damage is possible	A
S1	2	Corruption of the signal passed onto the D pin. If there is no limiting resistor in the switch path, then device damage is possible.	A
GND	3	Device is unpowered and not functional. Observe that the absolute maximum ratings for all pins of the device are met, otherwise device damage may be plausible.	A
VDD	4	There is no effect; this is normal operation.	D
EN	5	Enable is stuck high. Can no longer turn off the device	B
IN	6	Address is stuck high. Cannot control the switch states.	B
VSS	7	Device is unpowered and not functional. Observe that the absolute maximum ratings for all pins of the device are met, otherwise device damage may be plausible.	A
S2	8	Corruption of the signal passed onto the D pin. If there is no limiting resistor in the switch path, then device damage is possible.	A

Table 4-6. Pin FMA for Device Pins Short-Circuited to VSS

Pin Name	Pin No.	Description of Potential Failure Effect(s)	Failure Effect Class
D	1	Corruption of the signal passed onto the S pins. If there is no limiting resistor in the switch path, then device damage is possible.	A
S1	2	Corruption of the signal passed onto the D pin. If there is no limiting resistor in the switch path, then device damage is possible.	A
GND	3	Controls are stuck high. Can no longer turn off the device	B
VDD	4	Possible damage to the device if signal voltage is negative. Observe that the absolute maximum ratings for all pins of the device are met, otherwise device damage may be plausible.	A
EN	5	Possible damage to the device if signal voltage is negative. Observe that the absolute maximum ratings for all pins of the device are met, otherwise device damage may be plausible.	A
IN	6	Possible damage to the device if signal voltage is negative. Observe that the absolute maximum ratings for all pins of the device are met, otherwise device damage may be plausible.	A
VSS	7	There is no effect; this is normal operation.	D
S2	8	Corruption of the signal passed onto the D pin. If there is no limiting resistor in the switch path, then device damage is possible.	A

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